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# BULD741

# High voltage fast-switching NPN power transistor

### Features

- High voltage capability
- Low spread of dynamic parameters
- Minimum lot-to-lot spread for reliable operation
- Very high switching speed

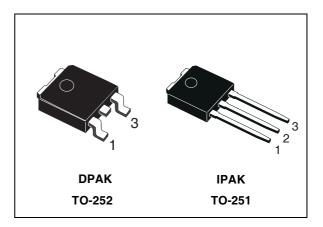
### Description

The device is manufactured using high voltage Multi-Epitaxial Planar technology for high switching speeds and high voltage capability.

Thanks to an increased intermediate layer, it has an intrinsic ruggedness which enables the transistor to withstand an high collector current level during breakdown condition, without using the transil protection usually necessary in typical converters for lamp ballast.

### Applications

- Electronic ballast for fluorescent lighting
- Switch mode power supplies.



#### Figure 1. Internal schematic diagram

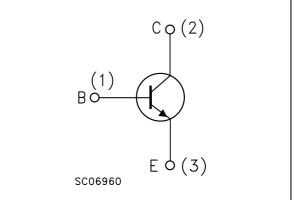


Table <sup>1</sup>	1	Device	summarv
Iable	1.	Device	Summary

Order codes	Marking	Package	Packaging
BULD741T4	BULD741	DPAK	Tape & reel
BULD741-1	BULD741	IPAK	Tube

# 1 Electrical ratings

Table 2. Absolute maximum rating	۱q
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Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-emitter voltage (V <sub>BE</sub> = 0)	1050	V
$V_{CEO}$	Collector-emitter voltage ( $I_B = 0$ )	400	V
$V_{\text{EBO}}$	Emitter-base voltage ( $I_C = 0$ , $I_B = 2A$ , $t_P < 10ms$ )	V <sub>(BR)EBO</sub>	V
۱ <sub>C</sub>	Collector current	2.5	Α
I <sub>CM</sub>	Collector peak current (t <sub>P</sub> < 5ms)	5	Α
Ι <sub>Β</sub>	Base current	1.5	Α
I <sub>BM</sub>	Base peak current (t <sub>P</sub> < 5ms)	3	Α
P <sub>tot</sub>	Total dissipation at $T_c = 25^{\circ}C$	30	W
T <sub>stg</sub>	Storage temperature	-65 to 150	°C
Т <sub>Ј</sub>	Max. operating junction temperature	150	°C

#### Table 3. Thermal data

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	4.16	°C/W

# 2 Electrical characteristics

( $T_{case} = 25^{\circ}C$  unless otherwise specified)

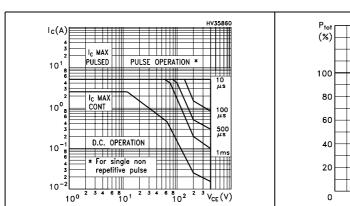
Symbol	Parameter Test conditions		litions	Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector cut-off current (V <sub>BE</sub> =0V)	V <sub>CE</sub> =1050V			0.2	10	μA
I <sub>CEO</sub>	Collector cut-off current (I <sub>B</sub> =0) V <sub>CE</sub> =400V			10	250	μA	
V <sub>(BR)EBO</sub>	Emitter-base breakdown voltage $(I_C = 0)$ $I_E = 1mA$		15	19	24	V	
V <sub>CEO(sus)</sub> <sup>(1)</sup>	Collector-emitter sustaining voltage (I <sub>B</sub> = 0)	I <sub>C</sub> =10mA		400	450		V
V <sub>CE(sat)</sub> <sup>(1)</sup>	Collector-emitter saturation voltage	I <sub>C</sub> =0.7A I <sub>C</sub> =2A	I <sub>B</sub> =0.14A I <sub>B</sub> =0.6A		0.15 0.5	0.5 1.5	V V
V <sub>BE(sat)</sub> <sup>(1)</sup>	Base-emitter saturation voltage	I <sub>C</sub> =2A	I <sub>B</sub> =0.6A		1.1	1.5	V
h <sub>FE</sub>	DC current gain	I <sub>C</sub> =0.1A I <sub>C</sub> =0.45A	V <sub>CE</sub> =5V V <sub>CE</sub> =3V	48 25	70 35	100 50	
t <sub>s</sub> t <sub>f</sub>	Resistive load Storage time Fall time	$V_{CC} = 125V$ $I_{B1} = -I_{B2} = 0.2A$ $V_{BE(off)} = -5V$	C		2.5 350	3.5 500	μs ns
E <sub>ar</sub>	Repetitive avalanche energy	L =2mH V <sub>BE(off)</sub> =-5V	C =1.8nF	5			mJ

Table 4. Electrical characteristics

Note (1) Pulsed duration =  $300\mu s$ , duty cycle  $\leq 1.5\%$ 

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### 2.1 Electrical characteristics (curves)



### Figure 2. Safe operating area

#### Figure 3. Derating curve

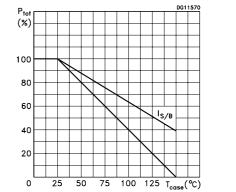


Figure 4. Output characteristics

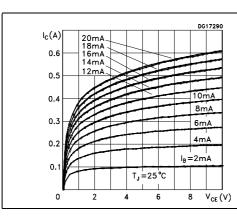
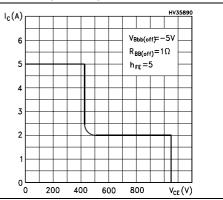
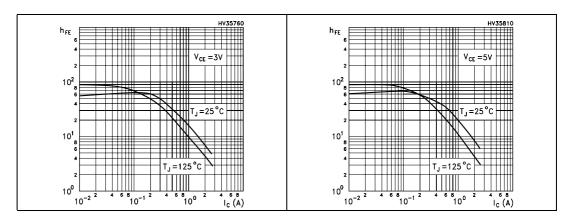


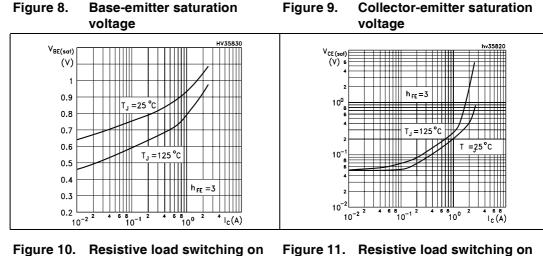
Figure 6. DC current gain

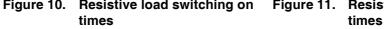


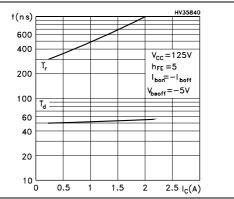


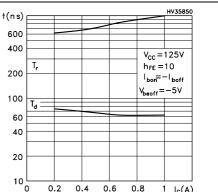












0.6

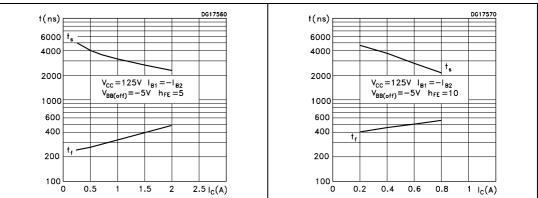
0.8

1 I<sub>C</sub>(A)

0.2

0.4

Figure 12. **Resistive load switching off** Figure 13. **Resistive load switching off** times times



### 2.2 Test circuits



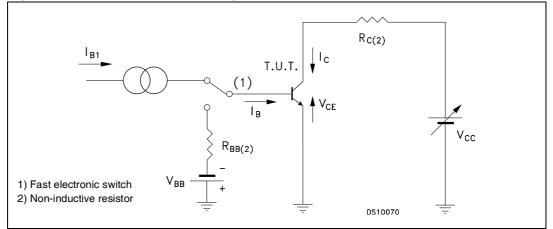
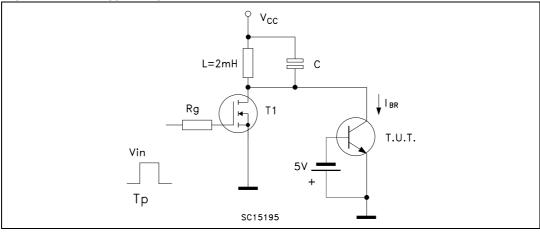


Figure 15. Energy rating test circuit



# 3 Package mechanical data

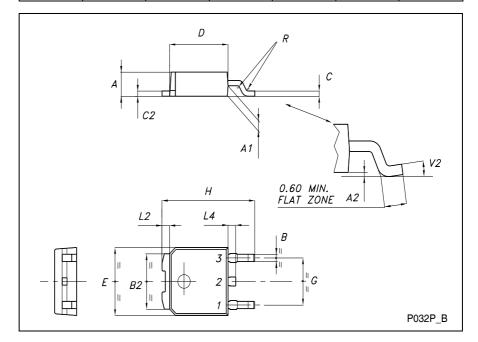
In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com



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DIM.	mm			inch			
2	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	2.20		2.40	0.087		0.094	
A1	0.90		1.10	0.035		0.043	
A2	0.03		0.23	0.001		0.009	
В	0.64		0.90	0.025		0.035	
B2	5.20		5.40	0.204		0.213	
С	0.45		0.60	0.018		0.024	
C2	0.48		0.60	0.019		0.024	
D	6.00		6.20	0.236		0.244	
E	6.40		6.60	0.252		0.260	
G	4.40		4.60	0.173		0.181	
Н	9.35		10.10	0.368		0.398	
L2		0.8			0.031		
L4	0.60		1.00	0.024		0.039	
V2	0°		8°	0°		0°	

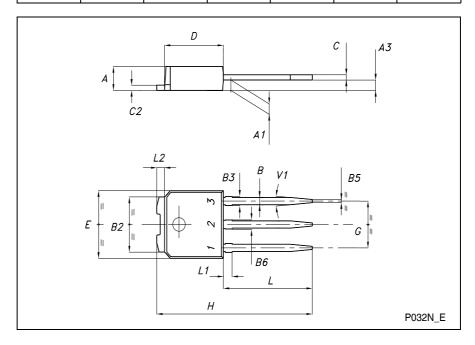
#### TO-252 (DPAK) MECHANICAL DATA



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DIM.	mm			inch			
Dilvi.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	2.20		2.40	0.087		0.094	
A1	0.90		1.10	0.035		0.043	
A3	0.70		1.30	0.028		0.051	
В	0.64		0.90	0.025		0.035	
B2	5.20		5.40	0.204		0.213	
B3			0.85			0.033	
B5		0.30			0.012		
B6			0.95			0.037	
С	0.45		0.60	0.018		0.024	
C2	0.48		0.60	0.019		0.024	
D	6.00		6.20	0.237		0.244	
Е	6.40		6.60	0.252		0.260	
G	4.40		4.60	0.173		0.181	
Н	15.90		16.30	0.626		0.642	
L	9.00		9.40	0.354		0.370	
L1	0.80		1.20	0.031		0.047	
L2		0.80	1.00		0.031	0.039	

### TO-251 (IPAK) MECHANICAL DATA



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# 4 Revision history

Date	Revision	Changes
20-Dec-2006	1	Initial release.
09-Jul-2007	2	Updated package names in page 1, added figure 4, updated figure 12 and 13.

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